

MacDermid Alpha Launches Ultra-Low Temperature Solder and 5G Solutions at Productronica China 2020

(Waterbury, CT USA) – June 18th, 2020 – The Assembly Solutions division of MacDermid Alpha Electronics Solutions, a world leader in the production of electronics soldering and bonding materials, will be introducing its ultra-low temperature solder and 5G solutions at the Productronica China show from July 3-5, 2020, at the National Exhibition and Convention Center in Shanghai.

MacDermid Alpha's new ultra-low temperature solder paste ALPHA® OM-220 paired with the ALPHA ULT1 alloy has been designed for soldering low temperature components and substrates. This innovative chemistry enables peak reflow temperatures below 150 °C, making it ideal for the soldering of heat sensitive components and sub-assemblies. In addition, ALPHA OM-220 permits cascaded / hierarchical soldering, as well as novel hermetic sealing solutions.

MacDermid Alpha will also exhibit its innovative specialty processes and materials from its Circuitry, Assembly and Semiconductor Solutions divisions, that support the entire 5G electronics supply chain. The Circuitry Solutions division will introduce its co-developed solutions for 5G circuitry and niche metallization, the Assembly Solutions division will show high performance joining materials for 5G related electronics assemblies and the Semiconductor Solutions division will highlight its advanced electronics materials for 5G processing power.

Productronica China 2020

Date: July 3-5, 2020 (Friday to Sunday)

Venue: National Exhibition and Convention Center in Shanghai

Booth: Hall 5.1 A201

For more information on MacDermid Alpha's revolutionary soldering materials and 5G Solutions, please visit our booth at Productronica China **Hall 5.1 A201** or visit **MacDermidAlpha.com**.

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